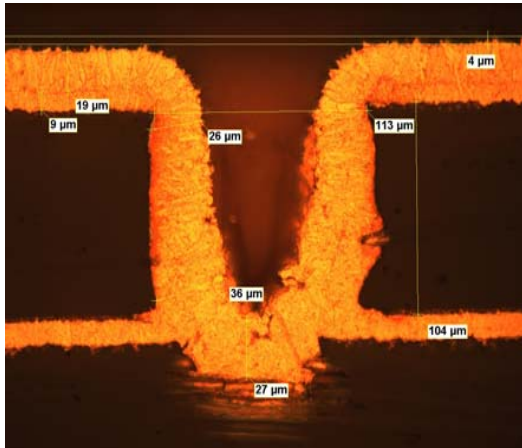


Vertical plated microvia + through-hole! Multi Step.

Diameter: 100 μm
Depth: 120 μm

AR = 1.2 : 1

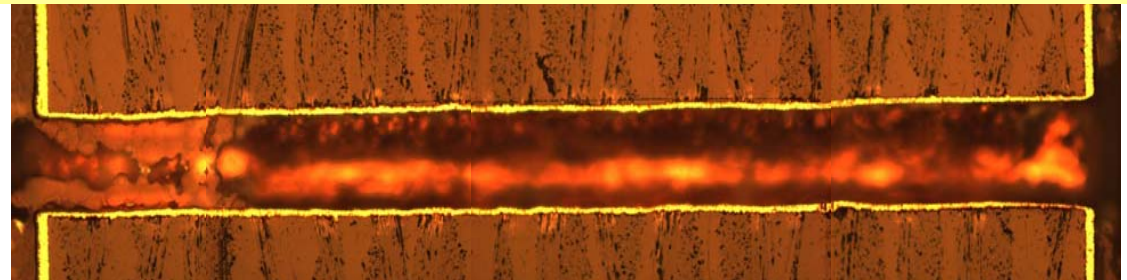


Bottom; 28.4 μm Cu
Surface; 20 μm Cu

TP = 142 %

Diameter: 0.3mm
Depth: 3.2mm

AR = 11 : 1



Cu(center hole) 15.0 μm
Cu(surface) 12.1 μm

TP = 125 %

Rectifier:
D2R- Series

Forward CD
25 ASF

Reverse CD

*3 Different Reverse CD
used in 3 steps; "batch-
programming".*